

# ICs for Communications

Multichannel Network Interface Controller for HDLC + Extensions MUNICH128X

PEB 20324 Version 2.2

Hardware Reference Manual 04.99



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**Edition 04.99 Published by Infineon Technologies AG i. Gr., SC, Balanstraße 73, 81541 München**

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<span id="page-2-0"></span>

### **Preface**

The MUNICH128X is a 128-channel WAN Protocol Controller which provides four independent 24/32-channel HDLC controllers, each with a dedicated 64-channel DMA Controller and a Serial PCM Interface Controller. The device is offered in a 160 pin MQFP package, making it ideal for high-port-density applications.

### **Organization of this Document**

This Hardware Reference Manual is divided into 7 chapters. It is organized as follows:

- Chapter 1, Introduction Gives a general description of the product and its family, lists the key features, and presents some typical applications.
- Chapter 2, Pin Description Lists pin locations with associated signals, categorizes signals according to function, and describes signals.
- Chapter 3, Functional IC Description Gives a general functional overview of the MUNICH128X.
- Chapter 4, Electrical Characteristics Gives a detailed description of all electrical DC and AC characteristics and provides timing diagrams and values for all interfaces.
- Chapter 5, Test Modes Gives a detailed description of the JTAG boundary scan interface.
- Chapter 6, Package Outline

### **Related Documentation**

MUNICH128X Version 2.2 Prpgrammer's Reference Manual 03.99 DS1



### **Table of Contents** Page











<span id="page-6-0"></span>

## **1 Introduction**

The MUNICH128X is a 128-channel WAN Protocol Controller which provides four independent 24/32-channel HDLC controllers, each with a dedicated 64-channel DMA Controller and a Serial PCM Interface Controller. The device is offered in a 160 pin MQFP package, making it ideal for high-port-density applications.

The MUNICH128X provides capability for up to 128 full duplex serial PCM channels. The chip performs layer 2 HDLC formatting/deformatting or V.110 or X.30 protocols up to a data rate of 38.4 kbit/s (V.110) or 64 kbit/s (HDLC). The MUNICH128X also performs transparent transmission for DMI modes 0, 1, and 2. Processed data is transferred to host memory via the PCI interface or de-multiplexed bus interface.

The MUNICH128X is compatible with the LAPD ISDN (Integrated Services Digital Network) protocol specified by CCITT, as well as with HDLC, SDLC, LAPB and DMI protocols. It provides rate adaptation for time slot transmission from 64 kbit/s down to 8 kbit/s and the concatenation of time slots, supporting the ISDN H0, H11, H12 superchannels.



**Figure 1-1 Simplified Block Diagram**

#### <span id="page-7-0"></span>**Multichannel Network Interface Controller for HDLC + Extensions MUNICH128X PEB 20324**

**Version 2.2 CMOS**

### **1.1 Features**

**Four independent 24/32-channel HDLC PCM Controllers with common PCI interface.**

#### **Each of them provides:**

- Dedicated 1024 byte Tx Buffer
- Dedicated 1024 byte Rx Buffer
- Dedicated Serial PCM Interface Controller
	- T1 rates: 1.536, 1.544, 3.088, 6.176 Mbit/s
	- E1 rates: 2.048, 4.096, 8.192 Mbit/s
- Dedicated 64-channel DMA Controller
	- Supports linked-list buffer processing
	- 16-DWord Tx DMA FIFO
	- 16-DWord Rx DMA FIFO
	- 4-DWord burst of Rx descriptors
	- 3-DWord burst of Tx descriptors
	- n-DWord burst of configuration blocks (n is unlimited according the MUNICH128X, but internal port arbitration may lead to a lower typical burst size of 4 or 8 DWords)
- **Dynamic Programmable Channel Allocation**
	- Compatible with T1/DS1 24-channel and CEPT 32-channel PCM byte format
	- Concatenation of any, not necessarily consecutive, time slots to superchannels independently for receive and transmit direction
	- Support of H0, H11, H12 ISDN-channels
	- Subchanneling on each time slot possible





**P-MQFP-160-1**

Hardware Reference Manual 8 04.99



#### **Introduction**

- **Bit Processor Functions** (adjustable for each channel)
	- HDLC Protocol
		- Automatic flag detection
		- Shared opening and closing flag
		- Detection of interframe-time-fill change, generation of interframe-time-fill '1's or flags
		- Zero bit insertion
		- Flag stuffing and flag adjustment for rate adaption
		- CRC generation and checking (16 or 32 bits)
		- Transparent CRC option per channel and/or per message
		- Error detection (abort, long frame, CRC error, 2 categories of short frames, non-octet frame content)
		- ABORT/IDLE flag generation
	- V.110/X.30 Protocol
		- Automatic synchronization in receive direction, automatic generation of the synchronization pattern in transmit direction
		- E/S/X bits freely programmable in transmit direction, may be changed during transmission; changes monitored and reported in receive direction
		- Generation/detection of loss of synchronism
		- Bit framing with network data rates from 600 bit/s up to 38.4 Kbit/s
	- Transparent Mode A
		- Slot synchronous transparent transmission/reception without frame structure
		- Flag generation, flag stuffing, flag extraction, flag generation in the abort case with programmable flag
		- Synchronized data transfer for fractional T1/PRI channels
	- Transparent Mode B
		- $-$  Transparent transmission/reception in frames delimited by  $00<sub>H</sub>$  flags
		- Shared opening and closing flag
		- Flag stuffing, flag detection, flag generation in the abort case
		- Error detection (non octet frame content, short frame, long frame)
	- Transparent Mode R
		- Transparent transmission/reception with GSM 08.60 frame structure
		- $-$  Automatic 0000 $<sub>H</sub>$  flag generation/detection</sub>
		- Support of 40, 39 $\frac{1}{2}$ , 40 $\frac{1}{2}$  octet frames
		- Error detection (non octet frame contents, short frame, long frame)
	- Protocol Independent
		- Channel inversion (data, flags, IDLE code)
		- Format conventions as in CCITT Q.921 § 2.8
		- Data over- and underflow detected



**Introduction**

- **32 Bit / 33 MHz PCI 2.1 Interface**
- **32 Bit / 33 MHz De-multiplexed Bus Interface Option**
- **0.5** µ**m, 3.3 V-Optimized Technology**
- **3.3 V I/O Capability with 5.0 V Input Tolerance**
- **160-pin MQFP Package**

<span id="page-10-0"></span>

**Introduction**

### **1.2 Logic Symbol**



**Figure 1-2 Logic Symbol**

<span id="page-11-0"></span>

### **1.3 Typical Applications**

The MUNICH128X provides protocol processing and host memory buffer management for four independent T1/E1 PRI ports. As such, the MUNICH128X fits into a system between the framer or LIU/framer devices (e.g., the Siemens FALC<sup>®</sup>54/FALC<sup>®</sup>54-LH transceiver) and the host bus (e.g. PCI Bus), as illustrated in Figure 1-3.

The MUNICH128X provides four independent Serial PCM ports which connect directly into the framer devices. In PCI based systems a dedicated microcontroller or PCI bridge chip is necessary to configure the framer or LIU/framer devices.

Additionally, the MUNICH128X provides a PCI 2.1 interface which connects directly to the system PCI bus. Optionally, this bus can be configured in De-multiplexed Mode.



**Figure 1-3 System Integration of the MUNICH128X in PCI-Based System**

<span id="page-12-0"></span>



**Figure 1-4 System Integration of the MUNICH128X in De-multiplexed System**

<span id="page-13-0"></span>

### **1.4 Differences to the MUNICH32**

- 128-channel capability
- Symmetrical Rx and Tx Buffer Descriptor formats for faster switching
- Improved Tx idle channel polling process for significantly reducing bus occupancy of idle Tx channels
- Dedicated 1024 byte Tx Buffer
- Dedicated 1024 byte Rx Buffer
- Burst capability also on transmit and receive data sections (8 DWORDs)
- Additional PCM modes supported: 3.088 MBit/s, 6.176 MBit/s, 8.192 MBit/s
- 32 Bit / 33 MHz PCI 2.1 master/slave interface; this interface can be configured in De-mux mode
- Separate Rx and Tx Status Queues in host memory (the MUNICH128X provides one set for each of the four HDLC Controllers)
- Slave access to on-chip registers
- Time Slot-shift capability:
	- Programmable from -4 clock edges to +3 clock edges relative to the synchronization pulse
	- Programmable to sample Tx and/or Rx data at either falling or rising edge of clock
- Software initiated action request (via the Command Register)
- Tx End-of-Packet transmitted-on-wire interrupt capability for each channel
- Tx packet size increased to 64 Kbytes (HDLC mode)
- Rx packet size 8 Kbyte limit interrupt disable
- Tx data  $TRISTATE^{TM}$  control line
- Synchronized data transfer in TMA mode for complete transparency when using fractional T1/PRI
- Little/Big Endian data formats

<span id="page-14-0"></span>

#### **Pin Descriptions**

### **2 Pin Descriptions**

### **2.1 Pin Diagram**

(top view)



**Figure 2-1 Pin Configuration**



#### **Pin Descriptions**

Pin descriptions in **Tables [2-1](#page-16-0)** to **[2-8](#page-26-0)** are grouped by functional block, as shown by the heading for that group. Pin types are indicated by abbreviations:

#### **Signal Type Definitions:**

The following signal type definitions are partly taken from the PCI Specification Revision 2.1:



#### **Signal Name Conventions:**

- **NC** Not Connected Pin Such pins are not bonded with the silicon. Although any potential at these pins will not impact the device it is recommended to leave them unconnected. NC pins might be used for additional functionality in later versions of the device. Leaving them unconnected will guarentee hardware compatibility to later device versions.
- **Reserved** *Reserved* pins are for vendor specific use only and should be connected as recommended to guarantee normal operation.
- Note: The signal type definition specifies the functional usage of a pin. This does not reflect necessarily the implementation of a pin, e.g. a pin defined of signal type 'Input' may be implemented with a bidirectional pad.
- Note: All unused input or I/O pins without internal Pull-Up/Down resistor must be connected to a defined level either connected to  $V_{DD3} / V_{SS}$  or to a Pull-Up/Down resistor  $\left(\rightleftharpoons$  10k).

<span id="page-16-0"></span>





<span id="page-17-0"></span>

#### **Pin Descriptions**

### **Table 2-2 Pin Descriptions by Functional Block: Port 1 Serial Interface**



<span id="page-18-0"></span>

#### **Pin Descriptions**

### **Table 2-3 Pin Descriptions by Functional Block: Port 2 Serial Interface**



<span id="page-19-0"></span>

#### **Pin Descriptions**

### **Table 2-4 Pin Descriptions by Functional Block: Port 3 Serial Interface**



<span id="page-20-0"></span>























<span id="page-24-0"></span>



<span id="page-25-0"></span>

#### **Pin Descriptions**



### **Table 2-7 Pin Descriptions by Functional Block: Power Supply**

<span id="page-26-0"></span>

Pin No.	<b>Symbol</b>	<b>Type</b>	<b>Description</b>			
115	<b>TCK</b>		<b>JTAG Test Clock</b> A Pull-Up resistor to $V_{DD3}$ is recommended if boundary scan unit is not used.			
116	<b>TMS</b>		<b>JTAG Test Mode Select</b> A Pull-Up resistor to $V_{DD3}$ is recommended if boundary scan unit is not used.			
121	<b>TDI</b>		<b>JTAG Test Data Input</b> A Pull-Up resistor to $V_{DD3}$ is recommended if boundary scan unit is not used.			
120	<b>TDO</b>	O	<b>JTAG Test Data Output</b>			
119	<b>TRST</b>		<b>JTAG Reset</b> <b>TRST should be connected to VSS if boundary</b> scan unit is not used.			

**Table 2-8 Pin Descriptions by Functional Block: Test Interface**

<span id="page-27-0"></span>

## **3 Functional Description**

### **3.1 Functional Overview**

The MUNICH128X provides four independent "cores" as well as global functional blocks (see **Figure 3-1**).

### **3.2 Block Diagram**

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**Figure 3-1 Block Diagram**

<span id="page-28-0"></span>

### **3.3 Functional Blocks**

Each core consists of dedicated circuitry: Serial PCM Interface Controller, Configuration and State RAM (CSR), 24/32-channel HDLC Controller with internal Transmit and Receive Buffers, 64-Channel DMA Controller, and Register Set.

#### **3.3.1 Serial PCM Interface Controller**

This block controls both Parallel–to-Serial (Tx) and Serial-to-Parallel (Rx) conversion and PCM timing. Additionally, this block controls the multiplexing of channels through the HDLC controller, as well as switching for the test loops.

#### **3.3.2 Configuration and State RAM (CSR)**

This block contains internal RAM which maintains the state of each channel. The Multiplex Control Block of the Serial PCM Interface Controller handles the switching of the CSR information into and out of the 24/32-channel HDLC Controller.

#### **3.3.3 24/32-channel HDLC Controller**

The HDLC Controller performs protocol processing for each channel independently, based on the CSR information for each channel.



#### **3.3.3.1 Tx Block**

#### **Transmit Buffer (TB)**

The Tx Block of the HDLC Controller contains a 1024 byte buffer (TB) which may be allocated to all 32 channels of one cove equally (i.e., 2-DWords per channel) or may be allocated based on superchannel considerations (e.g., 8–DWords per channel for 8 channels).

#### **HDLC Protocol**

Bit stuffing, flag generation, flag stuffing and adjustment, and CRC generation (either 16 bit or 32-bit) are performed.

#### **V.110 and V.30 Protocol**

Bit framing from 600 bit/s to 38.4 Kbit/s, automatic generation of the synchronization pattern, generation of loss of synchronization, programmable E/SX bits (including during run-time) are performed.

#### **Transparent Mode A**

This mode supports slot synchronous, transparent transmission without frame structure. It provides flag generation, flag stuffing, flag generation in the abort case with programmable flag, and synchronized data transfer for fractional T1/E1 PRI applications.

#### **Transparent Mode B**

This mode supports transparent transmission in frames delimited by  $00<sub>H</sub>$  flags, shared closing and opening flag, flag stuffing and flag generation in the abort case.

#### **Transparent Mode R**

This mode supports transparent transmission with GSM 08.60 frame structure with automatic  $0000_H$  flag generation and support of 40, 39.5, and 40.5 octet frames.

#### **Protocol Independence**

Channel inversion (data, flags, idle code) follows the format conventions as in CCITT Q.921.



#### **3.3.3.2 Rx Block**

#### **Receive Buffer (RB)**

The Rx Block of the HDLC Controller contains a 1024 byte buffer (RB) which is allocated to channels via requests from the protocol controller, as determined by the received data for each channel.

#### **HDLC Protocol**

Flag detection (supports multiple flags between packets or a single flag shared as a closing flag and an opening flag between packets), abort character detection, idle code detection, zero-bit detection and deletion, packet length count, and CRC checking (either 16-bit or 32-bit) are performed.

#### **V.110 and V.30 Protocol**

Bit framing from 600 bit/s to 38.4 Kbit/s, automatic synchronization of the synchronization pattern, detection of loss of synchronization, programmable E/SX bits (including during run–time) are performed.

#### **Transparent Mode A**

Mode A supports slot synchronous transparent reception without frame structure. It provides flag detection, flag extraction and synchronized data transfer for fractional T1/ E1 PRI applications.

#### **Transparent Mode B**

This mode supports transparent reception in frames delimited by  $00_H$  flags. Sharing closing flag and opening flag, and flag detection.

#### **Transparent Mode R**

This mode supports transparent reception with GSM 08.60 frame structure with automatic  $0000_H$  flag detection. Support of 40, 39.5, and 40.5 octet frames, and error detection (non–octet frame contents, short frame, long frame).

#### **Protocol Independence**

Channel inversion (data, flags, idle code) follows the format conventions as in CCITT Q.921, data overflow and underflow detection.



### **3.3.3.3 64-channel DMA Controller Block**

This block controls memory address calculation, buffer management (including linkedlists) and interrupt processing. The 24/32-channel HDLC Controller has a dedicated DMA channel for each channel and direction. During run-time, the DMA Controller performs operations with host memory primarily as a bus master. This block provides 32 input and 32 output channels.

#### **3.3.3.4 Register Set**

This block provides configuration and control of the Serial PCM Interface Controller, the HDLC Controller and the DMA Controller. Also, a shared status register STAT provides status and interrupt information associated with each of the four cores.



### **3.4 Global Functional Blocks**

The MUNICH128X provides global functional blocks for the Internal Bus, Arbiter, and 32 Bit / 33 MHz PCI 2.1 Interface as well as De-multiplexed Bus Interface Controller.

#### **3.4.1 Internal Bus**

This block of the MUNICH128X interfaces the Bus Interface Controller to the four DMA Controllers. This is a 33 MHz, 32 Bit demultiplexed bus that operates in a synchronous, non–burst manner for data transfers and operates in a synchronous burst manner for descriptor transfers.

#### **3.4.2 Arbiter**

The Arbiter provides access control of the Internal Bus. A "round-robin" Arbiter is used which provides "fairness" for the four master DMA controllers.

#### **3.4.3 32 Bit / 33 MHz Bus Interface Controller**

The MUNICH128X may be configured either for 32 Bit / 33 MHz PCI bus operation or for a 32 Bit / 33 MHz De-multiplexed bus interface. The MUNICH128X input pins DPCI(1:0) are used to select the desired configuration.

The De-multiplexed bus interface is a synchronous interface very similar to the PCI interface with the following exceptions:

- 1. The W/ $\overline{R}$  input/output signal replaces the function of the PCI command nibble of the C/BE(3:0) bit field.
- 2. Note, that in DEMUX mode as in PCI mode the MUNICH128X provides only the first address of a Master burst read or write transaction. If burst transactions are not supported by the local bus environment, burst capability can be disabled by bit DBE in the global configuration register (CONF).

<span id="page-33-0"></span>

### **3.5 System Integration**

The MUNICH128X provides protocol processing and host memory buffer management for four independent T1/E1 PRI ports. As such, the MUNICH128X fits into a system between the framer or LIU/framer devices (e.g., the Siemens FALC**®**54/FALC**®**54-LH transceiver) and the host bus (e.g. PCI Bus), as illustrated in **Figure 3-1**.

The MUNICH128X provides four independent Serial PCM ports which connect directly into the framer devices. In PCI based systems a dedicated microcontroller or PCI bridge chip is necessary to configure the framer or LIU/framer devices.

Additionally, the MUNICH128X provides a PCI 2.1 interface which connects directly to the system PCI bus. Optionally, this bus can be configured in De-multiplexed Mode.



**Figure 3-1 System Integration of the MUNICH128X in PCI-Based System**

<span id="page-34-0"></span>



**Figure 3-2 System Integration of the MUNICH128X in De-multiplexed System**

<span id="page-35-0"></span>

#### **Operational Description**

## **4 Operational Description**

### **4.1 Operational Overview**

The MUNICH128X is a "channelized" WAN protocol controller that performs protocol processing on up to 128 full duplex serial PCM channels. It performs HDLC-based layer 2 protocol formatting and deformatting, as well as rate adaptation, for each of the 128 channels independently.

The MUNICH128X provides dedicated registers for each of the four HDLC controllers, with each set similar to the "core" registers of the MUNICH32X. Software developed for the "core" of the MUNICH32X requires minimal modification to run optimally on the MUNICH128X. The architecture of the register sets allows any number of HDLC controllers within an MUNICH128X device to operate with host software images that differ only in their offset from the PCI base address and their pointers into host memory.

Host software sets the operating mode, rate adaptation method and time slot assignment of each channel by configuring "blocks" (CCBs) within host memory.

During "run-time" the MUNICH128X performs all data and descriptor transfers as a bus master. Additionally, host software may access any register of a particular HDLC Controller within the MUNICH128X, with the device acting as a bus slave.

The MUNICH128X provides a single Status Register, which maintains information of all interrupt events for the controller.

<span id="page-36-0"></span>

## **5 Electrical Characteristics**

### **5.1 Important Electrical Requirements**



 $V_{\text{DD5}} = 5.0 \text{ V} \pm 0.25 \text{ V}$   $V_{\text{DD5 max}} = 5.25 \text{ V}$ 

During all MUNICH128X power-up and power-down situations the difference

 $|V_{DD5} - V_{DD3}|$  may not exceed 3.6V. The absolute maximums of  $V_{DD5}$  and  $V_{DD3}$  should never be exceeded.

Figure 5-1 shows that both  $V_{DD3}$  and  $V_{DD5}$  can take on any time sequence not exceeding a voltage difference of 3.6V, for up to 50 milliseconds at power-up and powerdown.Within 50 milliseconds of power-up the voltages must be within their respective absolute voltage limits. At power-down, within 50 milliseconds of either voltage going outside its operational range, the voltage difference should not exceed 3.6V and both voltages must be returned below 0.1V:



#### **Figure 5-1 Power-up and Power-down scenarios**

<span id="page-37-0"></span>



Similar criteria also apply to power down in case of power failure situations:

#### **Figure 5-2 Power-Failure scenarios**

<span id="page-38-0"></span>

#### **5.2 Absolute Maximum Ratings**

#### **Table 5-1 Absolute Maximum Ratings**



<sup>1)</sup> According to MIL-Std 883D, method 3015.7 and ESD Ass. Standard EOS/ESD-5.1-1993. The RF Pins 20, 21, 26, 29, 32, 33, 34 and 35 are not protected against voltage stress  $>$  300 V (versus  $V_S$  or GND). The high frequency performance prohibits the use of adequate protective structures.

Note: Stresses above those listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **5.3 Thermal Package Characteristics**

#### **Table 5-2 Thermal Package Characteristics**



<span id="page-39-0"></span>

### **5.4 Operating Range**



Note: In the operating range, the functions given in the circuit description are fulfilled.

<span id="page-40-0"></span>

### **5.5 DC Characteristics**

#### **a) Non-PCI Interface Pins**

### **Table 5-3 Non-PCI Interface Pins**  $T_A = 0$  to + 70 $^{\circ}$ C;  $V_{DD5} = 5$  V  $\pm$  5%,  $V_{DD3} = 3.3$  V  $\pm$  0.3 V,  $V_{SS} = 0$  V

<b>Parameter</b>		<b>Symbo</b>	<b>Limit Values</b>		<b>Unit</b>	<b>Test Condition</b>	
			min.	max.			
L-input voltage		$V_{\text{IL}}$	$-0.4$	0.8	$\vee$		
H-input voltage		$V_{\sf IH}$	2.0	$V_{\text{DD5}} + 0.4$	$\vee$		
L-output voltage		$V_\mathsf{QL}$		0.45	$\vee$	$I_{\text{OI}} = 7 \text{ mA}$ (pin TXD) $I_{\text{ol}} = 2 \text{ mA}$ (all others / non-PCI)	
H-output voltage		$V_{\rm QH}$	2.4		$\vee$	$I_{\text{QH}} = -400 \mu A$	
Power supply current	operational	$I_{CC3}$		< 300	mA	$V_{DD3}$ = 3.3 V, $V_{DD5} = 5.0 V,$ inputs at 0 $V/V_{DD3}$ , no output loads	
	power down (no clocks)	$I_{CC3}$		< 5	mA		
	operational	$I_{\rm CC5}$		< 1	mA	$V_{DD3} = 3.3 V,$ $V_{DD5} = 5.0 V,$ inputs at 0 $V/V_{DD3}$ , no output loads	
	power down (no clocks)	$I_{CC5}$		< 1	mA		
Peak Power supply current during RAM initialization process		$I_{\text{CC3Peak}}$		< 700	mA	$V_{DD3}$ = 3.3 V, $V_{DD5} = 5.0 V,$	
		$I_{\text{CC5Peak}}$		< 10	mA	inputs at 0 $V/V_{DD3}$ , no output loads, 300 PCI clocks after power-up	
Input leakage current Output leakage current		$I_{\sqcup}$ $I_{\mathsf{LQ}}$		10	μA	0 V < $V_{\text{IN}}$ < $V_{\text{DD}}$ to 0 V 0 V < $V_{\text{OUT}}$ < $V_{\text{DD}}$ to 0 V	

Note: The listed characteristics are ensured over the operating range of the integrated circuit. Typical characteristics specify mean values expected over the production spread. If not otherwise specified, typical characteristics apply at  $T_A = 25 \degree C$  and the given supply voltage.

Note: The electrical characteristics described in **section [5.2](#page-38-0)** also apply here!

<span id="page-41-0"></span>

### **b) PCI Pins**

According to the PCI specification V2.1 from June 1, 1995 (Chapter 4: Electrical Specification for 5 V signalling)

Note: According the electrical characteristics all DEMUX Interface pins (DPCI(1:0),  $A(27:2)$ ,  $W\overline{R}$ ) are treated as PCI Interface pins.

#### **5.6 Capacitances**

#### **a) Non-PCI Interface Pins**

#### **Table 5-4 Non-PCI Interface Pins**  $T_A = 25^{\circ}$ C;  $V_{DD5} = 5$  V  $\pm$  5%,  $V_{DD3} = 3.3$  V  $\pm$  0.3 V,  $V_{SS} = 0$  V



#### **b) PCI Pins**

According to the PCI specification V2.1 from June 1, 1995 (Chapter 4: Electrical Specification for 5 V signalling)

Note: According the electrical characteristics all DEMUX Interface pins DPCI(1:0),  $A(27:2)$ ,  $W/\overline{R}$ ) are treated as PCI Interface pins.

<span id="page-42-0"></span>

### **5.7 AC Characteristics**

#### **a) Non-PCI Interface Pins**

 $T_A = 0$  to + 70°C;  $V_{DD5} = 5$  V  $\pm$  5%;  $V_{DD3} = 3.3$  V  $\pm$  0.3 V

Inputs are driven to 2.4 V for a logical "1" and to 0.4 V for a logical "0". Timing measurements are made at 2.0 V for a logical "1" and at 0.8 V for a logical "0".

The AC testing input/output waveforms are shown below.





#### **b) PCI Pins**

According to the PCI specification V2.1 from June 1, 1995 (Chapter 4: Electrical Specification for 5 V signalling)

Note: According the electrical characteristics all DEMUX Interface pins DPCI(1:0),  $A(27:2)$ ,  $W\overline{R}$ ) are treated as PCI Interface pins.

<span id="page-43-0"></span>

### **5.7.1 PCI Bus Interface Timing**

The AC testing input/output waveforms are shown in **figures 5-2** and **5-3** below.







**Figure 5-3 PCI Input Timing Measurement Waveforms**





The timings below show the basic read and write transaction between an initiator (Master) and a target (Slave) device. The MUNICH128X is able to work both as master and slave.

<span id="page-44-0"></span>

As a master the MUNICH128X reads/writes data from/to host memory using DMA and burst. The slave mode is used by an CPU to access the MUNICH128X PCI Configuration Space and the on-chip registers.

### **5.7.1.1 PCI Read Transaction**

The transaction starts with an address phase which occurs during the first cycle when FRAME is activated (clock 2 in **figure [5-4](#page-45-0)**). During this phase the bus master (initiator) outputs a valid address on AD(31:0) and a valid bus command on  $\overline{C/BE}$ (3:0). The first clock of the first data phase is clock 3. During the data phase C/BE indicate which byte lanes on AD(31:0) are involved in the current data phase.

The first data phase on a read transaction requires a turn-around cycle. In **figure [5-4](#page-45-0)** the address is valid on clock 2 and then the master stops driving AD. The target drives the AD lines following the turnaround when DEVSEL is asserted. (TRDY cannot be driven until DEVSEL is asserted.) The earliest the target can provide valid data is clock 4. Once enabled, the AD output buffers of the target stay enabled through the end of the transaction.

A data phase may consist of a data transfer and wait cycles. A data phase completes when data is transferred, which occurs when both IRDY and TRDY are asserted. When either is deasserted a wait cycle is inserted. In the example below, data is successfully transferred on clocks 4, 6 and 8, and wait cycles are inserted on clocks 3, 5 and 7. The first data phase completes in the minimum time for a read transaction. The second data phase is extended on clock 5 because TRDY is deasserted. The last data phase is extended because IRDY is deasserted on clock 7.

The Master knows at clock 7 that the next data phase is the last. However, the master is not ready to complete the last transfer, so IRDY is deasserted on clock 7, and FRAME stays asserted. Only when IRDY is asserted can FRAME be deasserted, which occurs on clock 8.

<span id="page-45-0"></span>



**Figure 5-4 PCI Read Transaction**

<span id="page-46-0"></span>

#### **Electrical Characteristics**

### **5.7.1.2 PCI Write Transaction**

The transaction starts when FRAME is activated (clock 2 in **figure 5-5**). A write transaction is similar to a read transaction except no turnaround cycle is required following the address phase. In the example, the first and second data phases complete with zero wait cycles. The third data phase has three wait cycles inserted by the target. Both initiator and target insert a wait cycle on clock 5. In the case where the initiator inserts a wait cycle (clock 5), the data is held on the bus, but the byte enables are withdrawn. The last data phase is characterized by IRDY being asserted while the FRAME signal is deasserted. This data phase is completed when TRDY goes active (clock 8).



**Figure 5-5 PCI Write Transaction**

<span id="page-47-0"></span>

### **5.7.1.3 PCI Timing Characteristics**

When the MUNICH128X operates as a PCI Master (initiator) and it either reads or writes a burst – as controlled by the on-chip DMA controller – it does not deactivate  $IRDY$ between consecutive data. In other words, no wait states are inserted by the MUNICH128X as a transaction initiator. The numbers of wait states, inserted by the MUNICH128X as initiator are listed in **table 5-6**.





When the MUNICH128X operates as a PCI Slave (target), it inserts wait cycles by deactivating TRDY. The numbers of wait states, typically inserted by the MUNICH128X are listed in **table 5-6:**





The number of wait states inserted by the MUNICH128X as target is not critical because accesses to the MUNICH128X are usually kept to a minimum in a system.

<span id="page-48-0"></span>



#### **Figure 5-6 PCI Clock Specification**





Note: Rise and fall times are specified in terms of the edge rate measured in V/ns. This slew rate must be met across the minimum peak-to-peak portion of the clock waveform as shown in **figure 5-6**.

<span id="page-49-0"></span>



#### **Table 5-9 PCI Interface Signal Characteristics**

- Note 1Minimum times are measured with 0 pF equivalent load; maximum times are measured with 50 pF equivalent load.
- Note 2REQ and GNT are point-to-point signals. All other signals are bussed GNT setup (min) time: 10ns

<span id="page-50-0"></span>



### **5.7.2 De-multiplexed Bus Interface**





#### **Figure 5-8 Master Burst WRITE/READ Access in De-multiplexed Bus Configuration**

The timing provided in **Table 5-7** and **Table 5-8** can also be applied to the de-multiplexed bus interface.



#### <span id="page-51-0"></span>**Table 5-10 Additional De-multiplexed Interface Signal Characteristics**

Note: The PCI parity signal PAR is not generated in de-multiplexed mode. It is driven active low by the MUNICH128X.

<span id="page-52-0"></span>



### **5.7.3 PCM Serial Interface Timing**

**Figure 5-9 PCM Serial Interface Timing**

<span id="page-53-0"></span>





- Note: The frequency on the serial line **must** be smaller or equal to  $^{1}\!/_{\rm 8}$ the frequency on the  $\mu$ P bus for 1.536 MHz, 1.544 MHz, 2.048 MHz  $^{1}\!/_{\!4}$ th of the frequency on the  $\mu$ P bus for 4.096 MHz.
- Note: For complete internal or complete external loop  $t_{42}$  and  $t_{49}$  must be greater or equal to 3 times *T*.

<span id="page-54-0"></span>

### **5.7.4 System Interface Timing**



**Figure 5-10 System Interface Timing**

#### **Table 5-12 System Interface Timing**



<span id="page-55-0"></span>



### **5.7.5 JTAG-Boundary Scan Timing**

**Figure 5-11 JTAG-Boundary Scan Timing** 

#### **Table 5-13 JTAG-Boundary Scan Timing**



<span id="page-56-0"></span>

#### **Test Modes**

### **6 Test Modes**

### **6.1 Boundary Scan Unit**

In the MUNICH128X a Test Access Port (TAP) controller is implemented. The essential part of the TAP is a finite state machine (16 states) controlling the different operational modes of the boundary scan. Both, TAP controller and boundary scan, meet the requirements given by the JTAG standard: IEEE 1149.1. **Figure 6-1** gives an overview.



**Figure 6-1 Block Diagram of Test Access Port and Boundary Scan**

If no boundary scan operation is planned TRST has to be connected with  $V_{SS}$ . TMS and TDI do not need to be connected since pull-up transistors ensure high input levels in this case. Nevertheless it would be a good practice to put the unused inputs to defined levels. In this case, if the JTAG is not used:

TMS = TCK = '1' is recommended.

Test handling (boundary scan operation) is performed via the pins TCK (Test Clock), TMS (Test Mode Select), TDI (Test Data Input) and TDO (Test Data Output) when the TAP controller is not in its reset state, i.e. TRST is connected to  $V_{DD}$  or it remains unconnected due to its internal pull-up. Test data at TDI are loaded with a 4-MHz clock

<span id="page-57-0"></span>

#### **Test Modes**

signal connected to TCK. '1' or '0' on TMS causes a transition from one controller state to another; constant '1' on TMS leads to normal operation of the chip.

### **Table 6-1 Boundary Scan Sequence in MUNICH128X**

 $TDI \rightarrow$ 





#### **Test Modes**





#### **Test Modes**





#### **Test Modes**



-> TDO

An input pin (I) uses one boundary scan cell (data in), an output pin (O) uses two cells (data out, enable) and an I/O-pin (I/O) uses three cells (data in, data out, enable). Note that some output and input pins of the MUNICH128X are tested as I/O pins in boundary scan, hence using three cells. The boundary scan unit of the MUNICH128X contains a total of  $n = 275$  scan cells.

The right column of **[Table 6-1](#page-57-0)** gives the initialization values of the cells.

<span id="page-61-0"></span>

#### **Test Modes**

The desired test mode is selected by serially loading a 3-bit instruction code into the instruction register via TDI (LSB first); see **Table 6-2.**



#### **Table 6-2 Boundary Scan Test Modes**

**EXTEST** is used to examine the interconnection of the devices on the board. In this test mode at first all input pins **capture** the current level on the corresponding external interconnection line, whereas all output pins are held at constant values ('0' or '1', according to **[Table 6-1](#page-57-0)**). Then the contents of the boundary scan is **shifted** to TDO. At the same time the next scan vector is loaded from TDI. Subsequently all output pins are **updated** according to the new boundary scan contents and all input pins again capture the current external level afterwards, and so on.

**INTEST** supports internal testing of the chip, i.e. the output pins **capture** the current level on the corresponding internal line whereas all input pins are held on constant values ('0' or '1', according to **[Table 6-1](#page-57-0)**). The resulting boundary scan vector is **shifted** to TDO. The next test vector is serially loaded via TDI. Then all input pins are **updated** for the following test cycle.

Note: In capture IR-state the code '001' is automatically loaded into the instruction register, i.e. if INTEST is wanted the shift IR-state does not need to be passed.

**SAMPLE/PRELOAD** is a test mode which provides a snap-shot of pin levels during normal operation.

**IDCODE**: A 32-bit identification register is serially read out via TDO. It contains the version number (4 bits), the device code (16 bits) and the manufacturer code (11 bits). The LSB is fixed to '1'.



Note: Since in test logic reset state the code '011' is automatically loaded into the instruction register, the ID code can easily be read out in shift DR state which is reached by  $TMS = 0, 1, 0, 0$ .

**BYPASS**: A bit entering TDI is shifted to TDO after one TCK clock cycle.

<span id="page-62-0"></span>

**Package Outlines**

## **7 Package Outlines**



#### **Sorts of Packing**

SMD = Surface Mounted Device Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

Dimensions in mm

This datasheet has been downloaded from:

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